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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

T64 1082

APPL NUM 10082472	FILING DATE 02/22/2002	CLASS 438	SUBCLASS 101	GAU 282	EXAMINER ZARNEKE
**APPLICANTS: Yoshida Akito; 2827					
**CONTINUING DATA VERIFIED:					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB	DO NOT PUBLISH <input checked="" type="checkbox"/>	RESCIND <input type="checkbox"/>			
Foreign priority claimed 35 USC 119 conditions met Verified and Acknowledged Examiners's initials			ATTORNEY DOCKET NO W2K 1077		
TITLE : Stacking structure for semiconductor devices using a folded over flexible substrate and method therefor U.S.DEP'T. OF COMM./PAT.& TM-PTO-438L(Rev. 12-94)					

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner	DRAWING	
Amount Due	Date Paid		Sheets Drwg.	Figs.Drwg.
TERMINAL DISCLAIMER		PREPARED FOR ISSUE Application Examiner		
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